672-Pin Ultra FineLine Ball-Grid Array (UBGA) - Wire Bond - A:1.85

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information

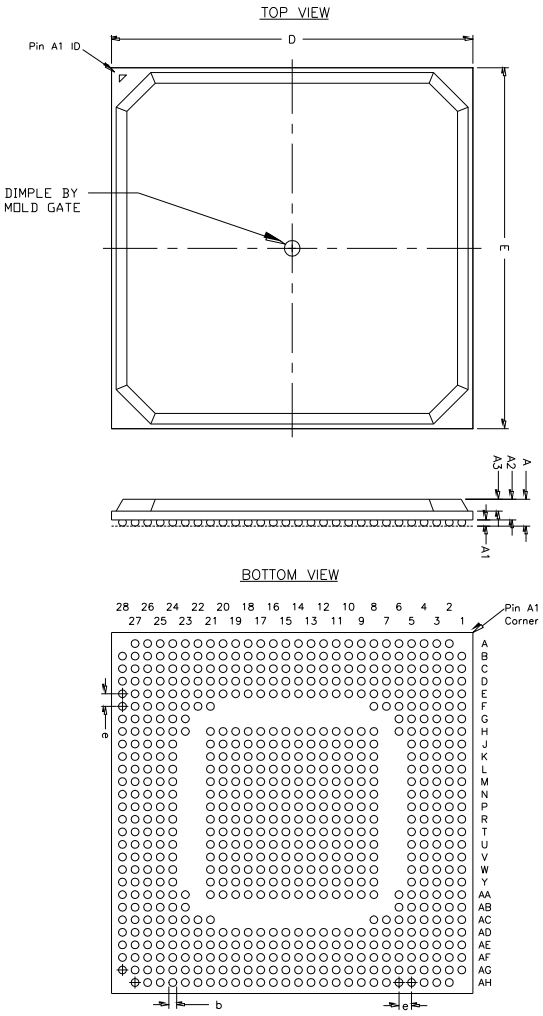
Description	Specification
Ordering Code Reference	U
Package Acronym	UBGA
Substrate Material	BT
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MO-308 Variation: AAJ-1
Lead Coplanarity	0.005 inch (0.12 mm)
Weight	2.2 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table

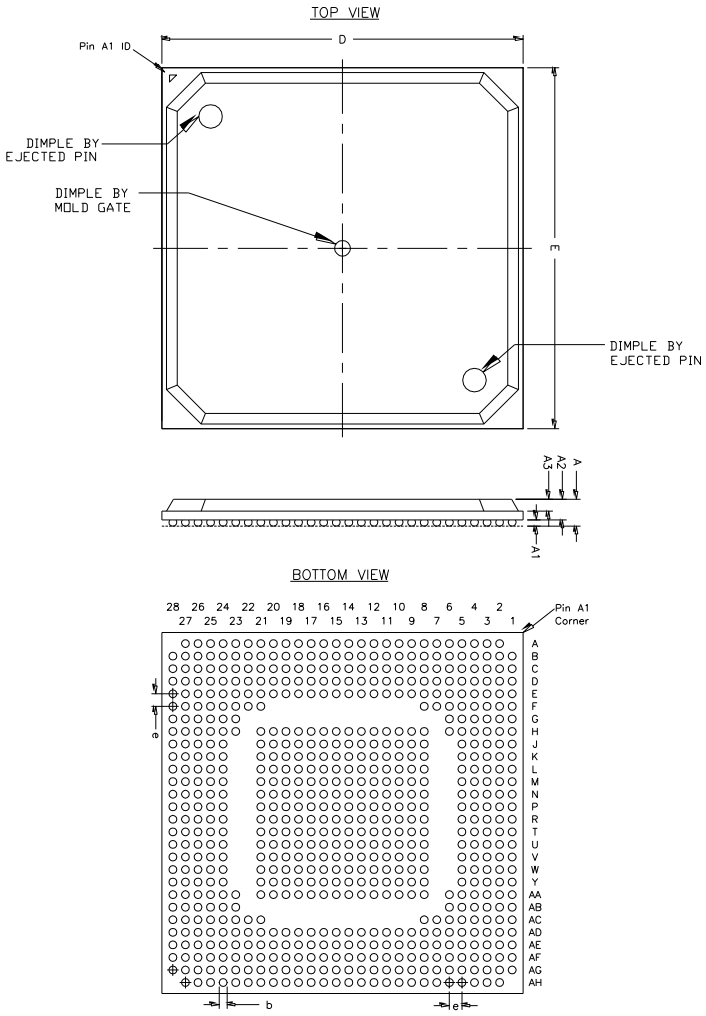
Symbol	Millimeters		
	Min.	Nom.	Max.
A	1.55	1.70	1.85
A1	0.35	0.40	0.45
A2	1.10	1.30	1.50
A3	0.71	0.76	0.81
D	23.00 BSC		
E	23.00 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		

Package Outline

OPTION 1



OPTION 2



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
April 2019	1.0	Initial release

now part of Intel

101 Innovation Drive
San Jose, CA 95134
www.altera.com

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